

CD4085BMS

CMOS Dual 2 Wide 2 Input AND-OR-INVERT Gate

December 1992

Features

- High Voltage Type (20V Rating)
- Medium Speed Operation
 - tPHL = 90ns
 - tPLH = 125ns (Typ.) at 10V
- · Individual Inhibit Controls
- 5V, 10V and 15V Parametric Ratings
- Standardized Symmetrical Output Characteristics
- 100% Tested for Quiescent Current at 20V
- Maximum Input Current of 1µA at 18V Over Full Package Temperature Range; 100nA at 18V and +25°C
- Noise Margin (Over Full Package/Temperature Range)
 - 1V at VDD = 5V
 - 2V at VDD = 10V
 - 2.5V at VDD = 15V
- Meets All Requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

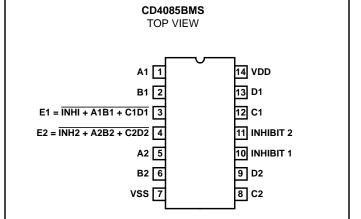
Description

CD4085BMS contains a pair of AND-OR-INVERT gates, each consisting of two 2 input AND gates driving a 3 input NOR gate. Individual inhibit controls are provided for both A-O-I gates...

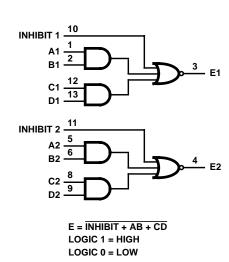
The CD4085BMS is supplied in these 14 lead outline packages:

Braze Seal DIP H4H Frit Seal DIP H₁B Ceramic Flatpack H5W

Pinout



Functional Diagram



VDD = 14 VSS = 7

Reliability Information Absolute Maximum Ratings Thermal Resistance nermal Resistance θ_{ja} Ceramic DIP and FRIT Package 80° C/W DC Supply Voltage Range, (VDD) -0.5V to +20V $_{20^{o}\text{C/W}}^{\theta_{jc}}$ (Voltage Referenced to VSS Terminals) Flatpack Package 70°C/W Input Voltage Range, All Inputs -0.5V to VDD +0.5V 20°C/W Maximum Package Power Dissipation (PD) at +125°C DC Input Current, Any One Input±10mA Operating Temperature Range.....-55°C to +125°C For TA = -55° C to $+100^{\circ}$ C (Package Type D, F, K).....500mW Package Types D, F, K, H For TA = $+100^{\circ}$ C to $+125^{\circ}$ C (Package Type D, F, K) Derate Storage Temperature Range (TSTG) -65°C to +150°C Linearity at 12mW/°C to 200mW Lead Temperature (During Soldering) +265°C Device Dissipation per Output Transistor 100mW At Distance 1/16 \pm 1/32 Inch (1.59mm \pm 0.79mm) from case for For TA = Full Package Temperature Range (All Package Types) 10s Maximum

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS

				GROUP A		LIN	IITS	
PARAMETER	SYMBOL	CONDITIONS (NOTE 1)	SUBGROUPS	TEMPERATURE	MIN	MAX	UNITS
Supply Current	IDD	VDD = 20V, VIN = VD	D or GND	1	+25°C	-	2	μΑ
				2	+125°C	-	200	μΑ
		VDD = 18V, VIN = VD	D or GND	3	-55°C	-	2	μА
Input Leakage Current	IIL	VIN = VDD or GND	VDD = 20	1	+25°C	-100	-	nA
				2	+125°C	-1000	-	nA
			VDD = 18V	3	-55°C	-100	-	nA
Input Leakage Current	IIH	VIN = VDD or GND	VDD = 20	1	+25°C	-	100	nA
				2	+125°C	-	1000	nA
			VDD = 18V	3	-55°C	-	100	nA
Output Voltage	VOL15	VDD = 15V, No Load	•	1, 2, 3	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOH15	VDD = 15V, No Load	(Note 3)	1, 2, 3	+25°C, +125°C, -55°C	14.95	-	V
Output Current (Sink)	IOL5	VDD = 5V, VOUT = 0.	4V	1	+25°C	0.53	-	mA
Output Current (Sink)	IOL10	VDD = 10V, VOUT = 0.5V		1	+25°C	1.4	-	mA
Output Current (Sink)	IOL15	VDD = 15V, VOUT = 1.5V		1	+25°C	3.5	-	mA
Output Current (Source)	IOH5A	VDD = 5V, VOUT = 4.	.6V	1	+25°C	-	-0.53	mA
Output Current (Source)	IOH5B	VDD = 5V, VOUT = 2.	5V	1	+25°C	-	-1.8	mA
Output Current (Source)	IOH10	VDD = 10V, VOUT = 9	9.5V	1	+25°C	-	-1.4	mA
Output Current (Source)	IOH15	VDD = 15V, VOUT = 1	13.5V	1	+25°C	-	-3.5	mA
N Threshold Voltage	VNTH	VDD = 10V, ISS = -10	μΑ	1	+25°C	-2.8	-0.7	V
P Threshold Voltage	VPTH	VSS = 0V, IDD = 10μ/	4	1	+25°C	0.7	2.8	V
Functional	F	VDD = 2.8V, VIN = VI	DD or GND	7	+25°C	VOH>	VOL <	V
		VDD = 20V, VIN = VD	D or GND	7	+25°C	VDD/2	VDD/2	
		VDD = 18V, VIN = VD	D or GND	8A	+125°C	1		
		VDD = 3V, VIN = VDD	or GND	8B	-55°C			
Input Voltage Low (Note 2)	VIL	VDD = 5V, VOH > 4.5	V, VOL < 0.5V	1, 2, 3	+25°C, +125°C, -55°C	-	1.5	V
Input Voltage High (Note 2)	VIH	VDD = 5V, VOH > 4.5	V, VOL < 0.5V	1, 2, 3	+25°C, +125°C, -55°C	3.5	-	V
Input Voltage Low (Note 2)	VIL	VDD = 15V, VOH > 13 VOL < 1.5V	3.5V,	1, 2, 3	+25°C, +125°C, -55°C	-	4	٧
Input Voltage High (Note 2)	VIH	VDD = 15V, VOH > 13 VOL < 1.5V	3.5V,	1, 2, 3	+25°C, +125°C, -55°C	11	-	V

implemented.

NOTES: 1. All voltages referenced to device GND, 100% testing being 3. For accuracy, voltage is measured differentially to VDD. Limit is 0.050V max.

2. Go/No Go test with limits applied to inputs.

TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

			GROUP A		LIM	IITS	
PARAMETER	SYMBOL	CONDITIONS (NOTES 1, 2)	SUBGROUPS	TEMPERATURE	MIN	MAX	UNITS
Propagation Delay	TPHL1	VDD = 5V, VIN = VDD or GND	9	+25°C	-	450	ns
Data			10, 11	+125°C, -55°C	-	608	ns
Propagation Delay	TPLH1	VDD = 5V, VIN = VDD or GND	9	+25°C	-	620	ns
Data			10, 11	+125°C, -55°C	-	837	ns
Propagation Delay	TPHL2	VDD = 5V, VIN = VDD or GND	9	+25°C	-	300	ns
Inhibit			10, 11	+125°C, -55°C	-	405	ns
Propagation Delay	TPLH2	VDD = 5V, VIN = VDD or GND	9	+25°C	-	500	ns
Inhibit			10, 11	+125°C, -55°C	-	675	ns
Transition Time	TTHL	VDD = 5V, VIN = VDD or GND	9	+25°C	-	200	ns
	TTLH		10, 11	+125°C, -55°C	i	270	ns

NOTES:

- 1. CL = 50pF, RL = 200K, Input TR, TF < 20ns.
- 2. -55°C and +125°C limits guaranteed, 100% testing being implemented.

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

					LIN	IITS		
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN MAX		UNITS	
Supply Current	IDD	VDD = 5V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	1	μΑ	
				+125°C	-	30	μА	
		VDD = 10V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	2	μА	
				+125°C	-	60	μΑ	
		VDD = 15V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	2	μΑ	
				+125°C	-	120	μΑ	
Output Voltage	VOL	VDD = 5V, No Load	1, 2	+25°C, +125°C, -55°C	-	50	mV	
Output Voltage	VOL	VDD = 10V, No Load	1, 2	+25°C, +125°C, -55°C	-	50	mV	
Output Voltage	VOH	VDD = 5V, No Load	1, 2	+25°C, +125°C, -55°C	4.95	-	V	
Output Voltage	VOH	VDD = 10V, No Load	1, 2	+25°C, +125°C, -55°C	9.95	-	V	
Output Current (Sink)	IOL5	VDD = 5V, VOUT = 0.4V	1, 2	+125°C	0.36	-	mA	
				-55°C	0.64	-	mA	
Output Current (Sink)	IOL10	VDD = 10V, VOUT = 0.5V	1, 2	+125°C	0.9	-	mA	
				-55°C	1.6	-	mA	
Output Current (Sink)	IOL15	VDD = 15V, VOUT = 1.5V	1, 2	+125°C	2.4	-	mA	
				-55°C	4.2	-	mA	
Output Current (Source)	IOH5A	VDD = 5V, VOUT = 4.6V	1, 2	+125°C	-	-0.36	mA	
				-55°C	-	-0.64	mA	
Output Current (Source)	IOH5B	VDD = 5V, VOUT = 2.5V	1, 2	+125°C	-	-1.15	mA	
				-55°C	-	-2.0 mA		
Output Current (Source)	IOH10	VDD = 10V, VOUT = 9.5V	1, 2	+125°C	-	-0.9	mA	
				-55°C	-	-2.6	mA	

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)

					LIN	IITS	
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Output Current (Source)	IOH15	VDD =15V, VOUT = 13.5V	1, 2	+125°C	-	-2.4	mA
				-55°C	-	-4.2	mA
Input Voltage Low	VIL	VDD = 10V, VOH > 9V, VOL < 1V	1, 2	+25°C, +125°C, -55°C	-	3	V
Input Voltage High	VIH	VDD = 10V, VOH > 9V, VOL < 1V	1, 2	+25°C, +125°C, -55°C	+7	-	V
Propagation Delay Data	TPHL1	VDD = 10V	1, 2, 3	+25°C	-	180	ns
		VDD = 15V	1, 2, 3	+25°C	-	130	ns
Propagation Delay Data	TPLH1	VDD = 10V	1, 2, 3	+25°C	-	250	ns
		VDD = 15V	1, 2, 3	+25°C	-	180	ns
Propagation Delay	TPHL2	VDD = 10V	1, 2, 3	+25°C	-	120	ns
Inhibit		VDD = 15V	1, 2, 3	+25°C	-	80	ns
Propagation Delay	TPLH2	VDD = 10V	1, 2, 3	+25°C	-	200	ns
Inhibit		VDD = 15V	1, 2, 3	+25°C	-	140	ns
Transition Time	TTHL	VDD = 10V	1, 2, 3	+25°C	-	100	ns
	TTLH	VDD = 15V	1, 2, 3	+25°C	-	80	ns
Input Capacitance	CIN	Any Input	1, 2	+25°C	-	7.5	pF

NOTES:

- 1. All voltages referenced to device GND.
- 2. The parameters listed on Table 3 are controlled via design or process and are not directly tested. These parameters are characterized on initial design release and upon design changes which would affect these characteristics.
- 3. CL = 50pF, RL = 200K, Input TR, TF < 20ns.

TABLE 4. POST IRRADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS

					LIM	IITS	
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Supply Current	IDD	VDD = 20V, VIN = VDD or GND	1, 4	+25°C	-	7.5	μΑ
N Threshold Voltage	VNTH	VDD = 10V, ISS = -10μA	1, 4	+25°C	-2.8	-0.2	V
N Threshold Voltage Delta	ΔVTN	VDD = 10V, ISS = -10μA	1, 4	+25°C	-	±1	V
P Threshold Voltage	VTP	VSS = 0V, IDD = 10μA	1, 4	+25°C	0.2	2.8	V
P Threshold Voltage Delta	ΔVΤΡ	VSS = 0V, IDD = 10μA	1, 4	+25°C	-	±1	V
Functional	F	VDD = 18V, VIN = VDD or GND VDD = 3V, VIN = VDD or GND	1	+25°C	VOH > VDD/2	VOL < VDD/2	V
Propagation Delay Time	TPHL TPLH	VDD = 5V	1, 2, 3, 4	+25°C	-	1.35 x +25°C Limit	ns

NOTES: 1. All voltages referenced to device GND.

3. See Table 2 for +25°C limit.

2. CL = 50pF, RL = 200K, Input TR, TF < 20ns.

4. Read and Record

TABLE 5. BURN-IN AND LIFE TEST DELTA PARAMETERS +25°C

PARAMETER	SYMBOL	DELTA LIMIT
Supply Current - MSI-1	IDD	± 0.2μA
Output Current (Sink)	IOL5	± 20% x Pre-Test Reading

TABLE 5. BURN-IN AND LIFE TEST DELTA PARAMETERS +25°C

PARAMETER	SYMBOL	DELTA LIMIT
Output Current (Source)	IOH5A	± 20% x Pre-Test Reading

TABLE 6. APPLICABLE SUBGROUPS

CONFORMANCE GROUP		MIL-STD-883 METHOD	GROUP A SUBGROUPS	READ AND RECORD
Initial Test (P	re Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
Interim Test 1	(Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
Interim Test 2	(Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
PDA (Note	1)	100% 5004	1, 7, 9, Deltas	
Interim Test 3 (Post Burn-In)		100% 5004	1, 7, 9	IDD, IOL5, IOH5A
PDA (Note	1)	100% 5004	1, 7, 9, Deltas	
Final Test		100% 5004	2, 3, 8A, 8B, 10, 11	
Group A		Sample 5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11	
Group B Subgroup B-5		Sample 5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11, Deltas	Subgroups 1, 2, 3, 9, 10, 11
Subgroup B-6 Sa		Sample 5005	1, 7, 9	
Group D		Sample 5005	1, 2, 3, 8A, 8B, 9	Subgroups 1, 2 3

NOTE: 1.5% Parameteric, 3% Functional; Cumulative for Static 1 and 2.

TABLE 7. TOTAL DOSE IRRADIATION

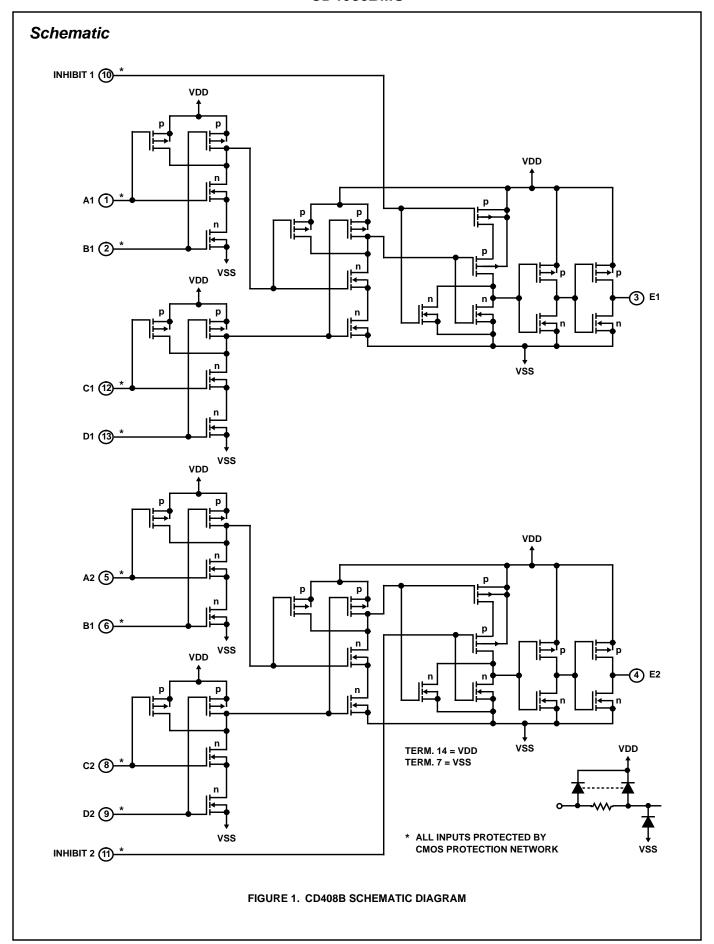
	MIL-STD-883	MIL-STD-883 TEST		READ AND RECORD		
CONFORMANCE GROUPS	METHOD	PRE-IRRAD	POST-IRRAD	PRE-IRRAD	POST-IRRAD	
Group E Subgroup 2	5005	1, 7, 9	Table 4	1, 9	Table 4	

TABLE 8. BURN-IN AND IRRADIATION TEST CONNECTIONS

					OSCILLATOR		
FUNCTION	OPEN	GROUND	VDD	9V \pm -0.5V	50kHz	25kHz	
Static Burn-In 1 Note 1	3, 4	1, 2, 5-13	14				
Static Burn-In 2 Note 1	3, 4	7	1, 2, 5, 6, 8-14				
Dynamic Burn- In Note 1	-	7	14	3, 4	1, 2, 5, 6, 8, 9, 12, 13	10, 11	
Irradiation Note 2	3, 4	7	1, 2, 5, 6, 8-14				

NOTE:

- 1. Each pin except VDD and GND will have a series resistor of 10K \pm 5%, VDD = 18V \pm 0.5V
- 2. Each pin except VDD and GND will have a series resistor of 47K \pm 5%; Group E, Subgroup 2, sample size is 4 dice/wafer, 0 failures, VDD = $10V \pm 0.5V$



Typical Performance Characteristics

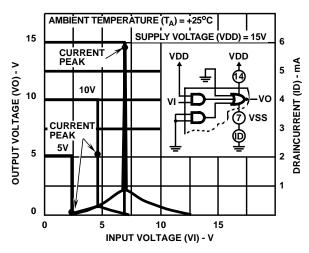


FIGURE 2. TYPICAL VOLTAGE AND CURRENT TRANSFER CHARACTERISTICS

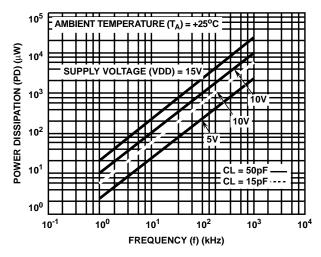


FIGURE 4. TYPICAL POWER DISSIPATION vs FREQUENCY

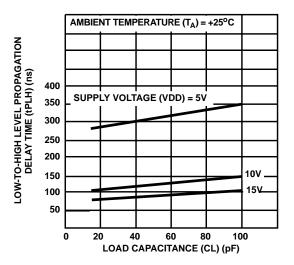


FIGURE 6. TYPICAL DATA LOW-TO-HIGH PROPAGATION DELAY TIME vs LOAD CAPACITANCE

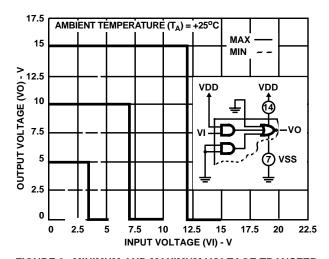


FIGURE 3. MINIMUM AND MAXIMUM VOLTAGE TRANSFER CHARACTERISTICS

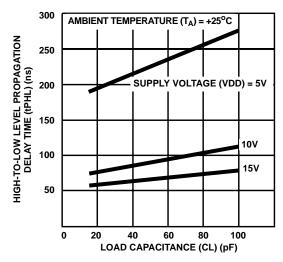


FIGURE 5. TYPICAL DATA HIGH-TO-LOW LEVEL PROPAGA-TION DELAY TIME vs LOAD CAPACITANCE

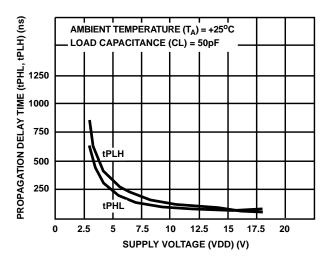


FIGURE 7. TYPICAL DATA PROPAGATION DELAY TIME vs SUPPLY VOLTAGE

Typical Performance Characteristics (Continued)

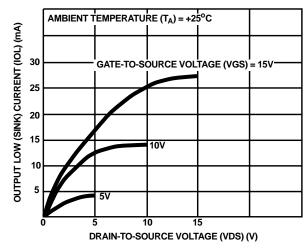


FIGURE 8. TYPICAL OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

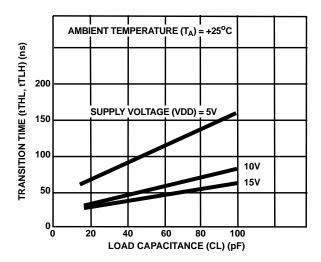


FIGURE 10. TYPICAL TRANSITION TIME vs LOAD CAPACITANCE

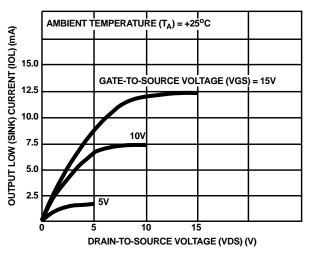


FIGURE 9. MINIMUM OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

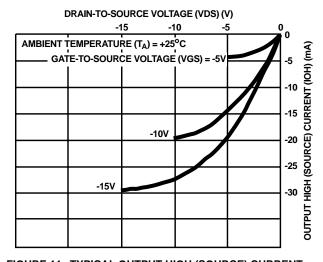


FIGURE 11. TYPICAL OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

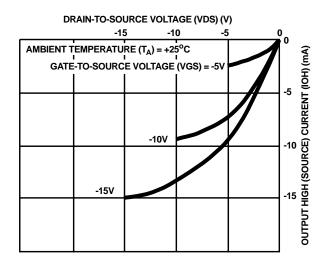
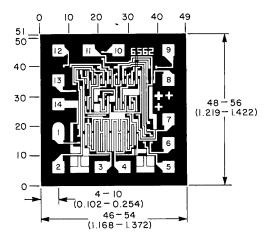


FIGURE 12. MINIMUM OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

Chip Dimensions and Pad Layout



Dimensions in parenthesis are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch).

METALLIZATION: Thickness: 11kÅ – 14kÅ, AL.

PASSIVATION: 10.4kÅ - 15.6kÅ, Silane

BOND PADS: 0.004 inches X 0.004 inches MIN **DIE THICKNESS:** 0.0198 inches - 0.0218 inches

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